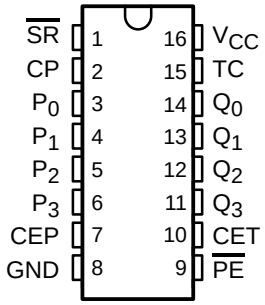
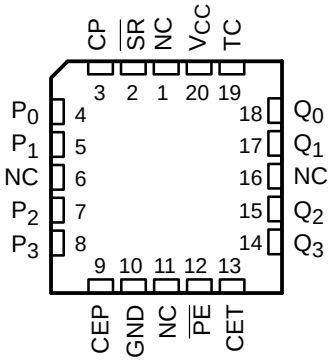
- **Function, Pinout, and Drive Compatible With FCT and F Logic**
- **Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions**
- **Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**
- **Matched Rise and Fall Times**
- **Fully Compatible With TTL Input and Output Logic Levels**
- **CY54FCT163T**
  - **32-mA Output Sink Current**
  - **12-mA Output Source Current**
- **CY74FCT163T**
  - **64-mA Output Sink Current**
  - **32-mA Output Source Current**

CY74FCT163CT . . . Q OR SO PACKAGE
(TOP VIEW)



CY54FCT163T . . . L PACKAGE
(TOP VIEW)



NC – No internal connection

description

The ’FCT163T devices are high-speed synchronous modulo-16 binary counters. They are synchronously presettable for application in programmable dividers. These devices have two types of count-enable (CEP and CET) inputs, plus a terminal-count (TC) output for versatility in forming synchronous multistaged counters. The ’FCT163T devices have a synchronous-reset ($\overline{SR}$) input that overrides counting and parallel loading, and allows the outputs to be reset simultaneously on the rising edge of the clock.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

PIN DESCRIPTION

NAME	DESCRIPTION
CEP	Count-enable parallel input
CET	Count-enable trickle input
CP	Clock pulse input (active rising edge)
$\overline{SR}$	Synchronous-reset input (active low)
P	Parallel data inputs
$\overline{PE}$	Parallel-enable input (active low)
Q	Flip-flop outputs
TC	Terminal-count output

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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ORDERING INFORMATION

T_A	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QSOP – Q	Tape and reel	5.8	CY74FCT163CTQCT	FT163-3
	SOIC – SO	Tube	5.8	CY74FCT163CTSOC	FCT163C
		Tape and reel	5.8	CY74FCT163CTSOCT	
–55°C to 125°C	LCC – L	Tube	11.5	CY54FCT163TLMB	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS				ACTION ON THE RISING CLOCK EDGE(S)
$\overline{SR}$	$\overline{PE}$	CET	CEP	
L	X	X	X	Reset (clear)
H	L	X	X	Load ($P_n \rightarrow Q_n$)
H	H	H	H	Count (incremental)
H	H	L	X	No change (hold)
H	H	X	L	No change (hold)

H = High logic level, L = Low logic level, X = Don't care

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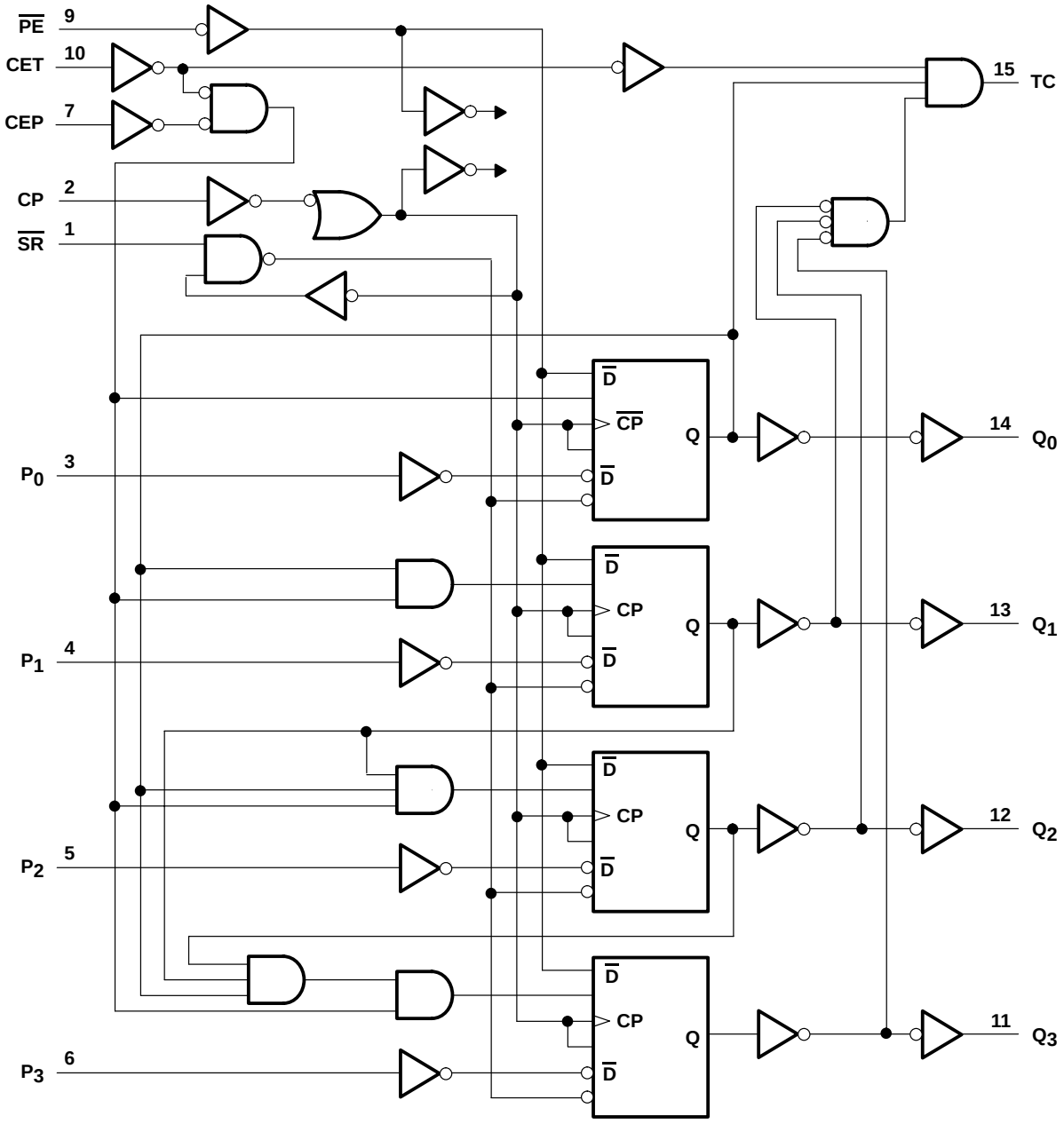
logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential . . . . . –0.5 V to 7 V
DC input voltage range . . . . . –0.5 V to 7 V
DC output voltage range . . . . . –0.5 V to 7 V
DC output current (maximum sink current/pin) . . . . . 120 mA
Package thermal impedance, θ_{JA} (see Note 1): Q package . . . . . 90°C/W
SO package . . . . . 57°C/W
Ambient temperature range with power applied, T_A . . . . . –65°C to 135°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY54FCT163T			CY74FCT163T			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			–12			–32	mA
I_{OL}	Low-level output current			32			64	mA
T_A	Operating free-air temperature	–55		125	–40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		CY54FCT163T			CY74FCT163T			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}	V_{CC} = 4.5 V,	I_{IN} = –18 mA		–0.7	–1.2				V
	V_{CC} = 4.75 V,	I_{IN} = –18 mA					–0.7	–1.2	
V_{OH}	V_{CC} = 4.5 V,	I_{OH} = –12 mA	2.4	3.3					V
	V_{CC} = 4.75 V	I_{OH} = –32 mA				2			
		I_{OH} = –15 mA				2.4	3.3		
V_{OL}	V_{CC} = 4.5 V,	I_{OL} = 32 mA		0.3	0.55				V
	V_{CC} = 4.75 V,	I_{OL} = 64 mA					0.3	0.55	
V_{hys}	All inputs			0.2			0.2		V
I_I	V_{CC} = 5.5 V,	V_{IN} = V_{CC}			5				µA
	V_{CC} = 5.25 V,	V_{IN} = V_{CC}						5	
I_{IH}	V_{CC} = 5.5 V,	V_{IN} = 2.7 V			±1				µA
	V_{CC} = 5.25 V,	V_{IN} = 2.7 V						±1	
I_{IL}	V_{CC} = 5.5 V,	V_{IN} = 0.5 V			±1				µA
	V_{CC} = 5.25 V,	V_{IN} = 0.5 V						±1	
I_{OS}‡	V_{CC} = 5.5 V,	V_{OUT} = 0 V	–60	–120	–225				mA
	V_{CC} = 5.25 V,	V_{OUT} = 0 V				–60	–120	–225	
I_{off}	V_{CC} = 0 V,	V_{OUT} = 4.5 V			±1			±1	µA
I_{CC}	V_{CC} = 5.5 V,	V_{IN} ≤ 0.2 V, V_{IN} ≥ V_{CC} – 0.2 V		0.1	0.2				mA
	V_{CC} = 5.25 V,	V_{IN} ≤ 0.2 V, V_{IN} ≥ V_{CC} – 0.2 V					0.1	0.2	
ΔI_{CC}	V_{CC} = 5.5 V, V_{IN} = 3.4 V§, f_1 = 0, Outputs open			0.2	2				mA
	V_{CC} = 5.25 V, V_{IN} = 3.4 V§, f_1 = 0, Outputs open						0.2	2	
I_{CCD}¶	V_{CC} = 5.5 V, Load mode, Outputs open, One bit switching at 50% duty cycle, CEP = CET = $\overline{PE}$ = GND, $\overline{SR}$ = V_{CC}, V_{IN} ≤ 0.2 V or V_{IN} ≥ V_{CC} – 0.2 V			0.06	0.12				mA/ MHz
	V_{CC} = 5.25 V, Load mode, Outputs open, One bit switching at 50% duty cycle, CEP = CET = $\overline{PE}$ = GND, $\overline{SR}$ = V_{CC}, V_{IN} ≤ 0.2 V or V_{IN} ≥ V_{CC} – 0.2 V						0.06	0.12	

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

¶ This parameter is derived for use in total power-supply calculations.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			CY54FCT163T			CY74FCT163T			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
I_C#	V_{CC} = 5.5 V, Load mode, f_0 = 10 MHz, Outputs open, $\overline{CEP}$ = CET = $\overline{PE}$ = GND, $\overline{SR}$ = V_{CC}	One bit switching at f_1 = 5 MHz at 50% duty cycle	$V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V		0.7	1.4				mA
			V_{IN} = 3.4 V or GND		1.2	3.4				
		Four bits switching at f_1 = 5 MHz at 50% duty cycle	$V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V		1.6	3.2‖				
			V_{IN} = 3.4 V or GND		2.9	8.2‖				
	V_{CC} = 5.25 V, f_0 = 10 MHz, Load mode, Outputs open, $\overline{CEP}$ = CET = $\overline{PE}$ = GND, $\overline{SR}$ = V_{CC}	One bit switching at f_1 = 5 MHz at 50% duty cycle	$V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V					0.7	1.4	
			V_{IN} = 3.4 V or GND					1.2	3.4	
		Four bits switching at f_1 = 5 MHz at 50% duty cycle	$V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V					1.6	3.2‖	
			V_{IN} = 3.4 V or GND					2.9	8.2‖	
C_i					5	10		5	10	pF
C_o					9	12		9	12	pF

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

$I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

I_C = Total supply current
I_{CC} = Power-supply current with CMOS input levels
ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)
D_H = Duty cycle for TTL inputs high
N_T = Number of TTL inputs at D_H
I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)
f_0 = Clock frequency for registered devices, otherwise zero
f_1 = Input signal frequency
N_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

‖ Values for these conditions are examples of the I_{CC} formula.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY54FCT163T		CY74FCT163CT		UNIT
			MIN	MAX	MIN	MAX	
t_w	Pulse duration, high or low	Clock (load)	5		4		ns
		Clock (count)	8		5		
t_{su}	Setup time, high or low	P before CP↑	5.5		3.5		ns
		$\overline{PE}$ or $\overline{SR}$ before CP↑	13.5		7.6		
		CEP or CET before CP↑	13		7.6		
t_h	Hold time, high or low	P after CP↑	2		1.5		ns
		$\overline{PE}$ or $\overline{SR}$ after CP↑	1.5		1		
		CEP or CET after CP↑	0		0		

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switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	CY54FCT163T		CY74FCT163CT		UNIT
				MIN	MAX	MIN	MAX	
t_{PLH}	Propagation delay ($\overline{PE}$ high)	CP	Q	2	11.5	1.5	5.8	ns
t_{PHL}				2	11.5	1.5	5.8	
t_{PLH}	Propagation delay ($\overline{PE}$ low)	CP	TC	2	10	1.5	5.2	ns
t_{PHL}				2	10	1.5	5.2	
t_{PLH}		CP	TC	2	16.5	1.5	7.8	ns
t_{PHL}				2	16.5	1.5	7.8	
t_{PLH}		CET	TC	1.5	9	1.5	4.4	ns
t_{PHL}				1.5	9	1.5	4.4	

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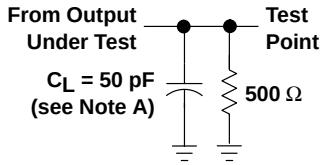
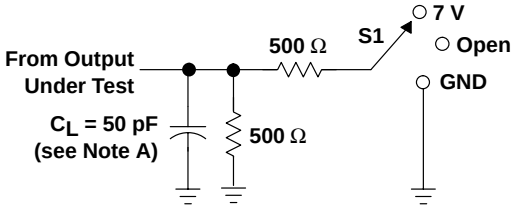
PARAMETER MEASUREMENT INFORMATION

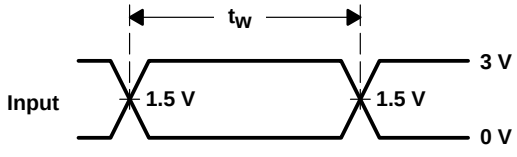


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

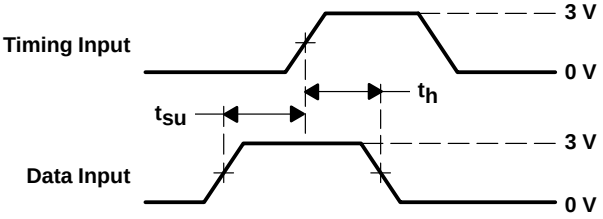


LOAD CIRCUIT FOR
3-STATE OUTPUTS

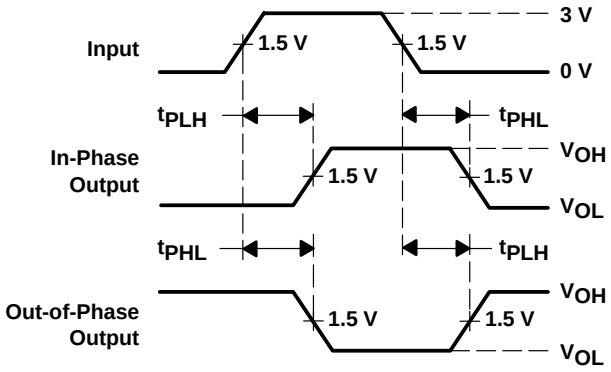
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



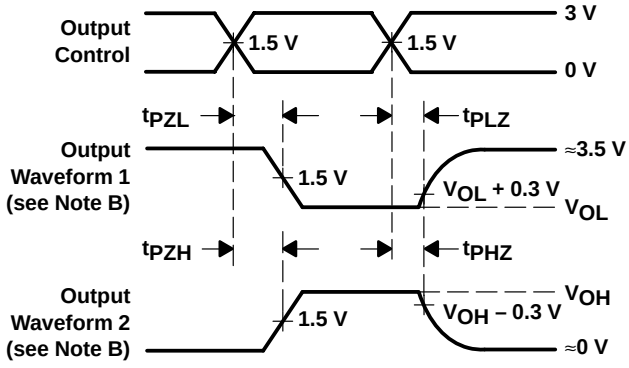
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CY54FCT163TLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
CY74FCT163CTQCT	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT163CTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT163CTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT163CTSOC	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT163CTSOCE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT163CTSOCG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT163CTSOCT	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT163CTSOCTE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT163CTSOCTG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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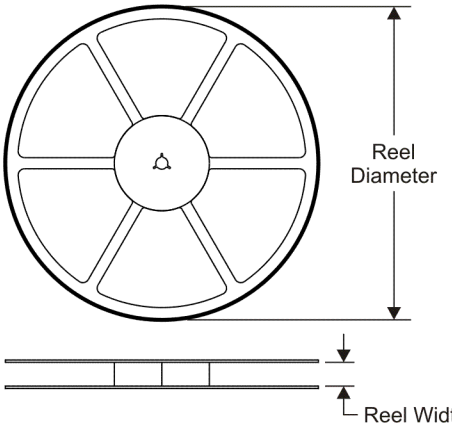
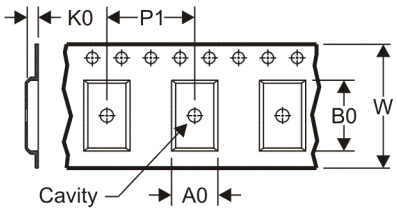
TAPE AND REEL INFORMATION

REEL DIMENSIONS

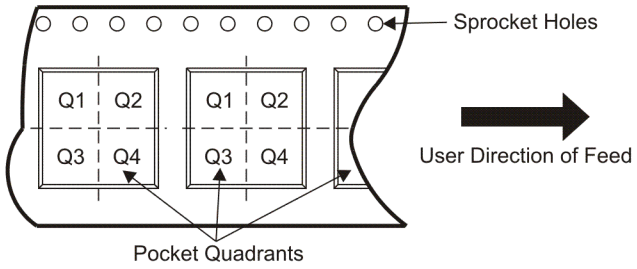


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT163CTSOCT	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

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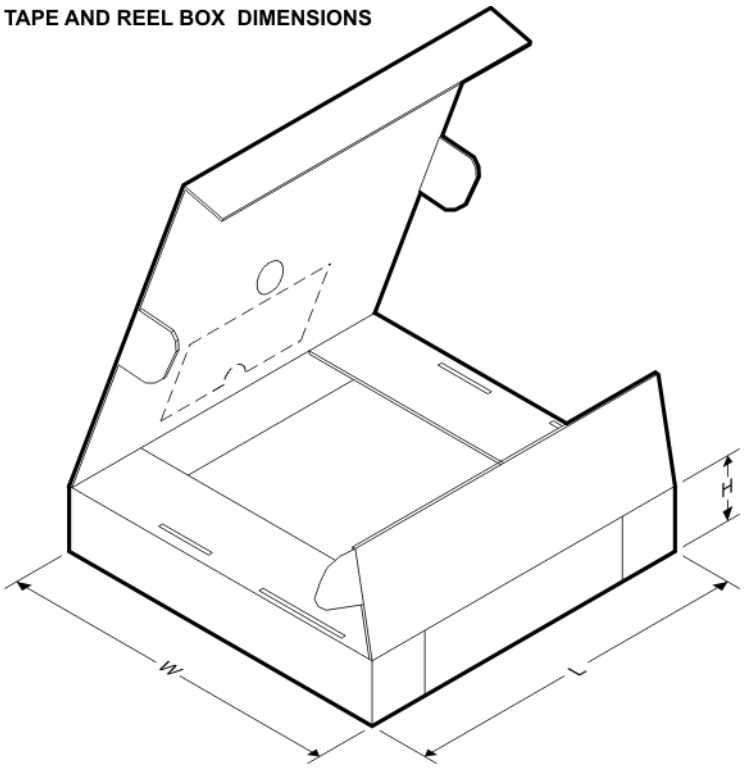
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT163CTSOCT	SOIC	DW	16	2000	346.0	346.0	33.0

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